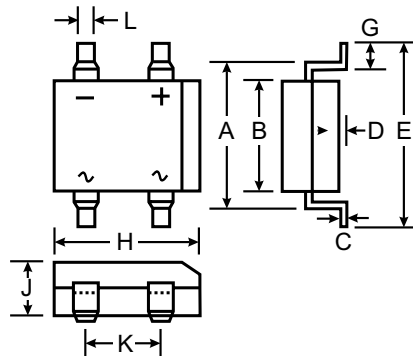


### Features

- Glass Passivated Die Construction
- Diffused Junction
- Low Forward Voltage Drop, High Current Capability
- Surge Overload Rating to 50A Peak
- Designed for Surface Mount Application
- Plastic Material - UL Flammability Classification Rating 94V-0
- UL Listed Under Recognized Component Index, File Number E94661

### Mechanical Data

- Case: Molded Plastic
- Terminals: Solder Plated Leads, Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Case
- Weight: 0.38 grams (approx.)
- Mounting Position: Any
- Marking: Type Number



DF-S		
Dim	Min	Max
A	7.40	7.90
B	6.20	6.50
C	0.22	0.30
D	0.076	0.33
E	—	10.40
G	1.02	1.53
H	8.13	8.51
J	2.40	3.40
K	5.00	5.20
L	1.00	1.20
All Dimensions in mm		

### Maximum Ratings and Electrical Characteristics @ T<sub>A</sub> = 25°C unless otherwise specified

Single phase, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristic	Symbol	DF 15005S	DF 1501S	DF 1502S	DF 1504S	DF 1506S	DF 1508S	DF 1510S	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	50	100	200	400	600	800	1000	V
Working Peak Reverse Voltage	V <sub>RWM</sub>								
DC Blocking Voltage	V <sub>R</sub>								
RMS Reverse Voltage	V <sub>R(RMS)</sub>	35	70	140	280	420	580	700	V
Average Forward Rectified Current @ T <sub>A</sub> = 40°C	I <sub>O</sub>	1.5							A
Non-Repetitive Peak Forward Surge Current, 8.3 ms single half-sine-wave superimposed on rated load (JEDEC method)	I <sub>FSM</sub>	50							A
Forward Voltage (per element) @ I <sub>F</sub> = 1.5A	V <sub>FM</sub>	1.1							V
Peak Reverse Current at rated @ T <sub>A</sub> = 25°C	I <sub>RM</sub>	10							μA
DC blocking voltage (per element) @ T <sub>A</sub> = 125°C		500							
I <sup>2</sup> t Rating for Fusing (t<8.3ms)	I <sup>2</sup> t	10.4							A <sup>2</sup> s
Typical Junction Capacitance per element (Note 1)	C <sub>j</sub>	25							pF
Typical Thermal Resistance, Junction to Ambient (Note 2)	R <sub>θJA</sub>	40							°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150							°C

Notes: 1. Measured at 1.0 MHz and Applied Reverse Voltage of 4.0V DC.

2. Thermal resistance, junction to ambient, measured on PC board with 5.0mm<sup>2</sup> (0.03mm thick) land areas.

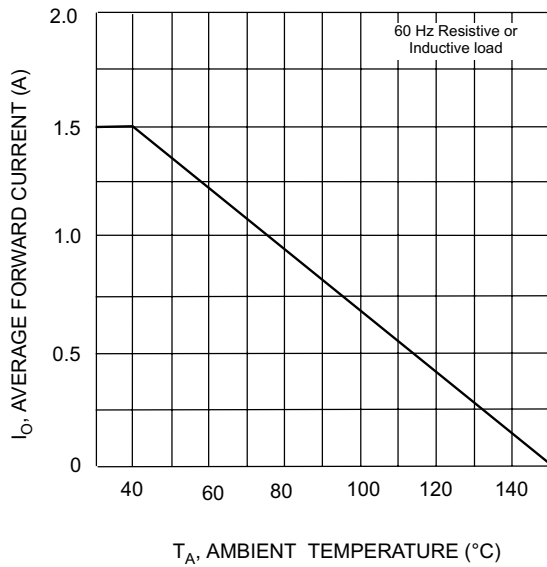


Fig. 1 Output Current Derating Curve

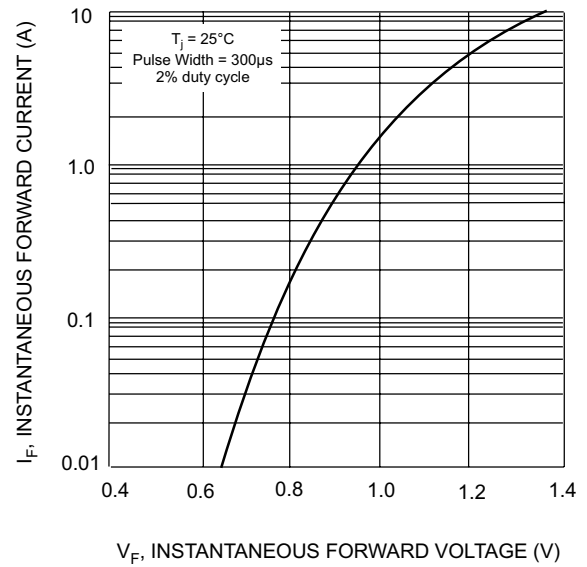


Fig. 2 Typ Forward Characteristics (per element)

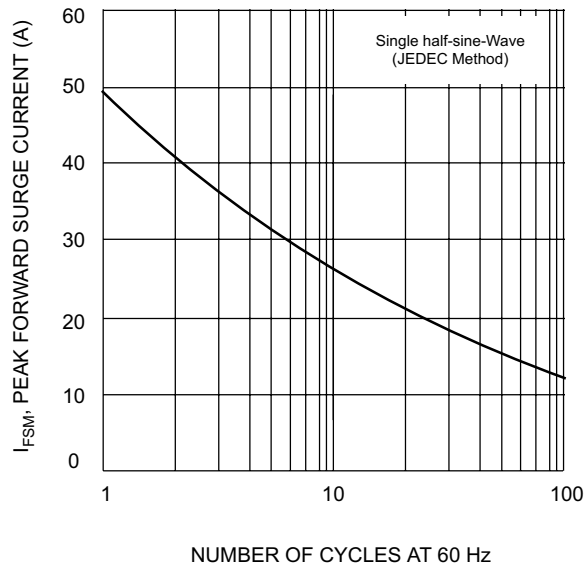


Fig. 3 Max Non-Repetitive Peak Forward Surge Current

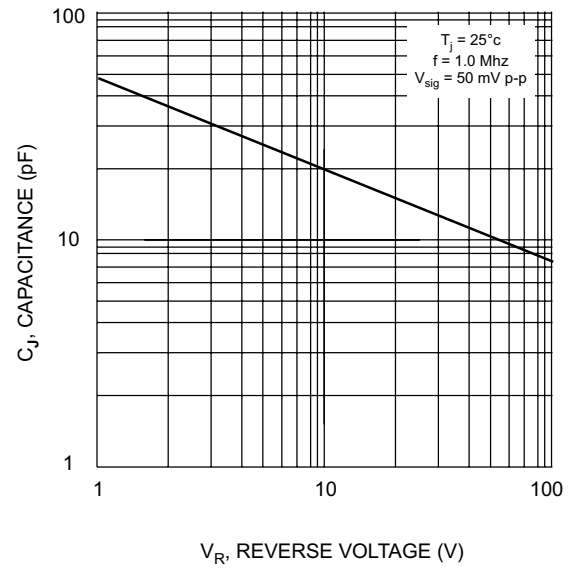


Fig. 4 Typ Junction Capacitance (per element)

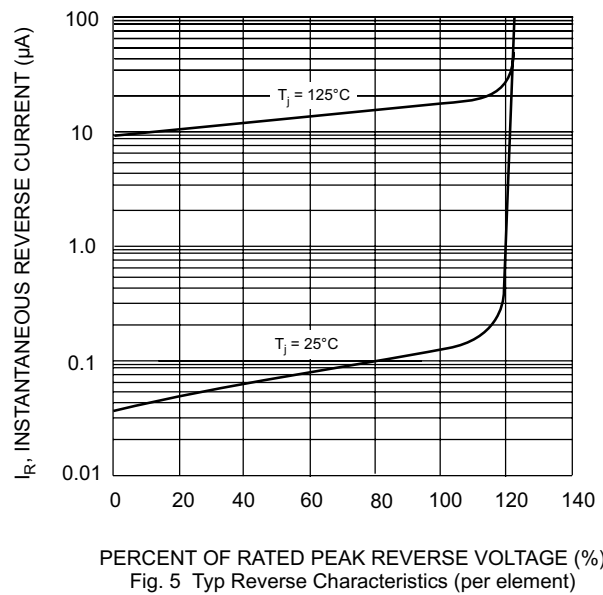


Fig. 5 Typ Reverse Characteristics (per element)